Semiconductor Device Type:	3BX	008 SOIC 3.90mm(.150in) NiPdAu Plastic Gull Wing Small Outline	Termination Base Alloy: Copper Alloy (Cu)		
Basic Substance	**CAS Number**	**"Contained In" Sub-Component**	**% Total Weight**	**mg/part**	**ppm**
Silica, vitreous (or fused)	60676-86-0	Mold Compound	59.543	44.657	595,425
Epoxy Resin	Trade Secret	Mold Compound	6.094	4.571	60,944
Phenolic Resin	Trade Secret	Mold Compound	4.203	3.152	42,030
Carbon Black	1333-86-4	Mold Compound	0.210	0.158	2,102
Copper	7440-50-8	Lead Frame	26.841	20.131	268,408
Iron	7439-89-6	Lead Frame	0.040	0.030	404
Phosphorous	7723-14-0	Lead Frame	0.011	0.008	108
Zinc (Metal)	7440-66-6	Lead Frame	0.008	0.006	81
Silver	7440-22-4	Die Attach	0.077	0.058	770
Epoxy resin	68475-94-5	Die Attach	0.020	0.015	200
Copper(II) oxide	1317-38-0	Die Attach	0.003	0.002	30
Silicon	7440-21-3	Chip (Die)	0.950	0.713	9,500
Copper (Cu)	7440-50-8	Wire Bond	0.488	0.366	4,875
Palladium (Pd)	7440-05-3	Wire Bond	0.012	0.009	115
Gold (Au)	7440-57-5	Wire Bond	0.001	0.001	10
Nickle (Ni)	7440-02-0	Plating on external leads (pins)	1.391	1.043	13,905
Palladium (Pd)	7440-05-3	Plating on external leads (pins)	0.098	0.073	975
Gold (Au)	7440-57-5	Plating on external leads (pins)	0.012	0.009	120
		TOTALS:	**100.000**	**75.000**	**1,000,000**

0.0750 g Total Mass

Package Homogeneous Materials

J-STD-609A Product Marking and/or Pkg. Labeling e4

52.54	**(mg) Total**	**Mold Compound**	**% ot Total Weight**	**70.05**
	Silica, vitreous (or fused)	60676-86-0	85.00	
	Epoxy Resin	Trade Secret	8.70	
	Phenolic Resin	Trade Secret	6.00	
	Carbon Black	1333-86-4	0.30	
		Total	**100.00**	
20.18	**(mg) Total**	**Lead Frame**	**% of Total Weight**	**26.90**
	Copper	7440-50-8	99.78	
	Iron	7439-89-6	0.15	
	Phosphorous	7723-14-0	0.04	
	Zinc (Metal)	7440-66-6	0.03	
		Total	**100.00**	
0.08	**(mg) Total**	**Die Attach**	**% of Total Weight**	**0.10**
	Silver	7440-22-4	77.00	
	Epoxy resin	68475-94-5	20.00	
	Copper(II) oxide	1317-38-0	3.00	
		Total	**100.00**	
0.71	**Total (mg)**	**Chip (Die)**	**% of Total Weight**	**0.95**
	Doped Silicon	7440-21-3	100	
		Total	**100.00**	
0.38	**(mg) Total**	**Wire Bond**	**% of Total Weight**	**0.50**
	Copper (Cu)	7440-50-8	97.50	
	Palladium (Pd)	7440-05-3	2.30	
	Gold (Au)	7440-57-5	0.20	
		Total	**100.00**	
1.13	**(mg) Total**	**Plating on external leads (pins)**	**% of Total Weight**	**1.50**
	Nickle (Ni)	7440-02-0	92.70	
	Palladium (Pd)	7440-05-3	6.50	
	Gold (Au)	7440-57-5	0.80	
		Total	**100.00**	
75.00				100.00

This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero)

Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.

If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.

Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/

The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.

Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.

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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table